

Low-pressure plasma system V230-3G-R-R

Reel-to-reel unit for etching, cleaning or activation



The reel-to-reel system V230-3G-R-R is designed for the low-pressure plasma treatment of foils, leadframes and circuit boards.

The plasma process operates during winding of the substrates (cleaning, etching or activation treatments possible).

Rolls with interleaf (liner) can be treated as well.

Options

- Vacuum pump
- Ozone trap
- Further gas channels
- kHz generator (40 kHz)
- MHz generator (13,56 MHz)
- Variable interfaces
- Exhaust gas scrubber
- Soft-start and slow-vent

Technical data

Dimensions of the system (W x D x H): approx. 2,591 x D 1,030 x H 2,060 mm

Roll dimensions: max. 400 mm dia., material width: max. 70 mm

Microwave power generators: 3 pcs. à 2.45 GHz, flexible power from 100 W up to max. 1,200 W

Gas supply: 2 gas channels with mass flow controllers and magnetic valves

Vacuum connection: DN 63 ISO-K

Power supply: 230/400 V, 50/60 Hz, 10 kW (without vacuum pump)

Process control: PLC control unit

Vacuum gauge: capacitance manometer (independent of gas type)



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